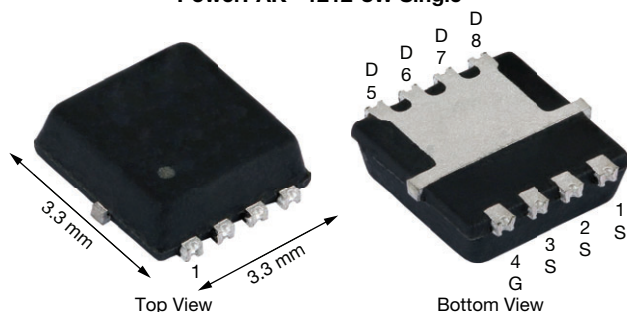


Automotive P-Channel 12 V (D-S) 175 °C MOSFET

PowerPAK® 1212-8W Single

Marking code: Q055

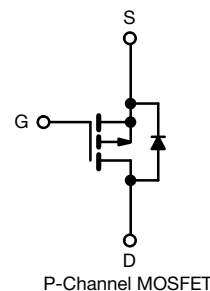
PRODUCT SUMMARY

V_{DS} (V)	-12
$R_{DS(on)}$ (Ω) at $V_{GS} = -4.5$ V	0.0150
$R_{DS(on)}$ (Ω) at $V_{GS} = -2.5$ V	0.0220
I_D (A)	-16
Configuration	Single
Package	PowerPAK 1212-8W

FEATURES

- TrenchFET® power MOSFET
- AEC-Q101 qualified
- 100 % R_g and UIS tested
- Material categorization:
for definitions of compliance please see
www.vishay.com/doc?99912

AUTOMOTIVE
GRADE

RoHS
COMPLIANT
HALOGEN
FREE


ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-source voltage	V_{DS}	-12	V
Gate-source voltage ^a	V_{GS}	± 8	
Continuous drain current ^b	I_D	$T_C = 25$ °C	A
		$T_C = 125$ °C	
Continuous source current (diode conduction) ^b	I_S	-16	
Pulsed drain current ^c	I_{DM}	-64	
Single pulse avalanche current	I_{AS}	-16	mJ
Single pulse avalanche energy	E_{AS}	12.8	
Maximum power dissipation	P_D	$T_C = 25$ °C	W
		$T_C = 125$ °C	
Operating junction and storage temperature range	T_J, T_{stg}	-55 to +175	°C
Soldering recommendations (peak temperature) ^{e, f}		260	

THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	LIMIT	UNIT
Junction-to-ambient	R_{thJA}	81	°C/W
Junction-to-case (drain)	R_{thJC}	3.8	

Notes

- Recommended maximum positive V_{GS} ratings: +4V in continuous mode, +8V in PWM mode with $\leq 25\%$ duty
- Package limited
- Pulse test; pulse width ≤ 300 μ s, duty cycle $\leq 2\%$
- When mounted on 1" square PCB (FR4 material)
- See solder profile (www.vishay.com/doc?73257)
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components



SPECIFICATIONS (T _C = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0, I _D = -250 μA		-12	-	-	V
Gate-source threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250 μA		-0.45	-0.6	-1.0	
Gate-source leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 8 V		-	-	± 100	nA
Zero gate voltage drain current	I _{DSS}	V _{GS} = 0 V	V _{DS} = -12 V	-	-	-1	μA
		V _{GS} = 0 V	V _{DS} = -12 V, T _J = 125 °C	-	-	-50	
		V _{GS} = 0 V	V _{DS} = -12 V, T _J = 175 °C	-	-	-150	
On-state drain current ^a	I _{D(on)}	V _{GS} = -4.5 V	V _{DS} ≥ -5 V	20	-	-	A
Drain-source on-state resistance ^a	R _{DS(on)}	V _{GS} = -4.5 V	I _D = -13.5 A	-	0.0106	0.0150	Ω
		V _{GS} = -4.5 V	I _D = -13.5 A, T _J = 125 °C	-	-	0.0205	
		V _{GS} = -4.5 V	I _D = -13.5 A, T _J = 175 °C	-	-	0.0233	
		V _{GS} = -2.5 V	I _D = -12 A	-	0.0166	0.0220	
Forward transconductance ^b	g _{fs}	V _{DS} = -6 V, I _D = -13.5 A		-	41	-	S
Dynamic ^b							
Input capacitance	C _{iss}	V _{GS} = 0 V	V _{DS} = -6 V, f = 1 MHz	-	2260	3050	pF
Output capacitance	C _{OSS}			-	815	1100	
Reverse transfer capacitance	C _{rss}			-	630	850	
Total gate charge ^c	Q _g	V _{GS} = -8 V	V _{DS} = -6 V, I _D = -4 A	-	53.6	81	nC
Gate-source charge ^c	Q _{gs}			-	4	-	
Gate-drain charge ^c	Q _{gd}			-	9.6	-	
Gate resistance	R _g	f = 1 MHz		1.55	3.1	4.65	Ω
Turn-on delay time ^c	t _{d(on)}	V _{DD} = -6 V, R _L = 1.5 Ω I _D ≅ -4 A, V _{GEN} = -8 V, R _g = 1 Ω		-	11	20	ns
Rise time ^c	t _r			-	6	12	
Turn-off delay time ^c	t _{d(off)}			-	58	90	
Fall time ^c	t _f			-	26	40	
Source-Drain Diode Ratings and Characteristic ^b							
Pulsed current ^a	I _{SM}			-	-	-64	A
Forward voltage	V _{SD}	I _F = -10 A, V _{GS} = 0 V		-	-0.81	-1.1	V
Body diode reverse recovery time	t _{rr}	I _F = -5 A, di/dt = 100 A/μs		-	44	88	ns
Body diode reverse recovery charge	Q _{rr}			-	32	64	nC
Reverse recovery fall time	t _a			-	22	-	ns
Reverse recovery rise time	t _b			-	22	-	
Body diode peak reverse recovery current	I _{RM(REC)}			-	-1.2	-	A

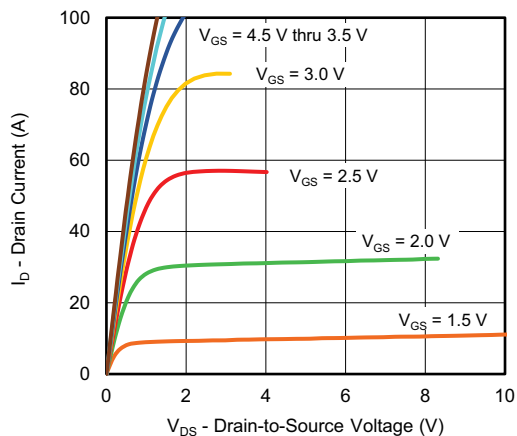
Notes

- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$
b. Guaranteed by design, not subject to production testing
c. Independent of operating temperature

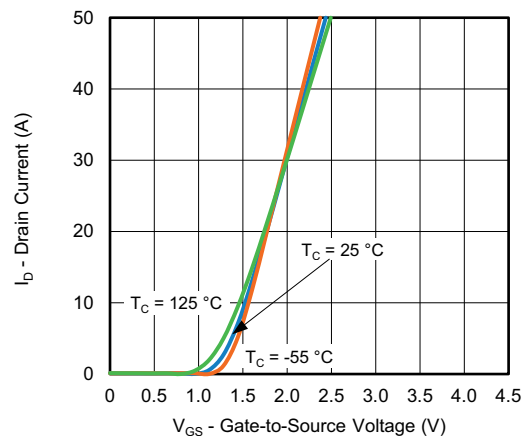
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



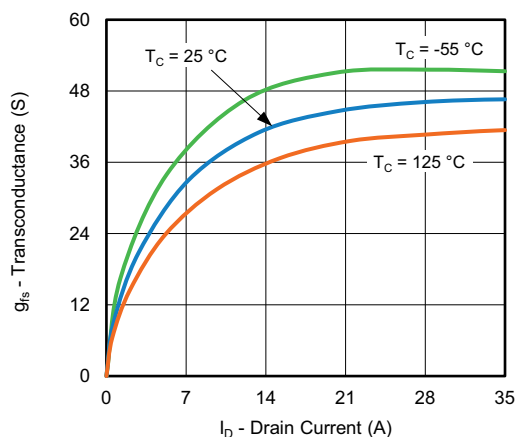
TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)



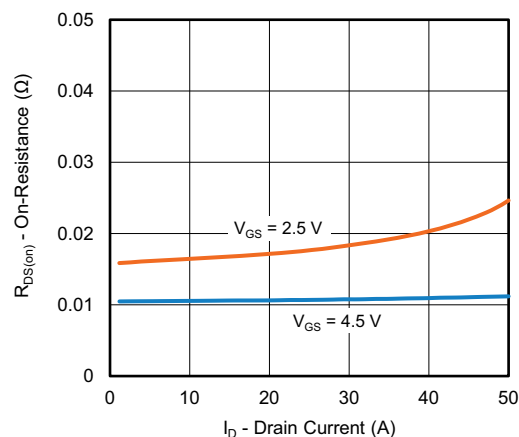
Output Characteristics



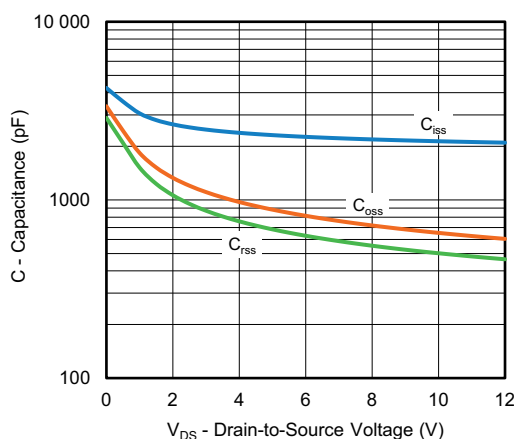
Transfer Characteristics



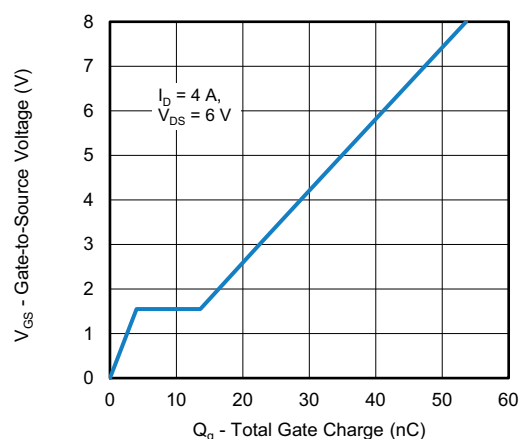
Transconductance



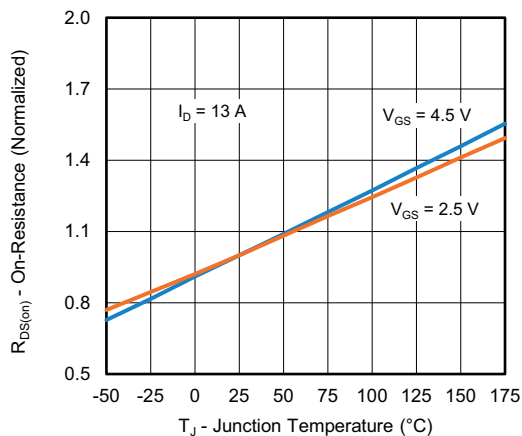
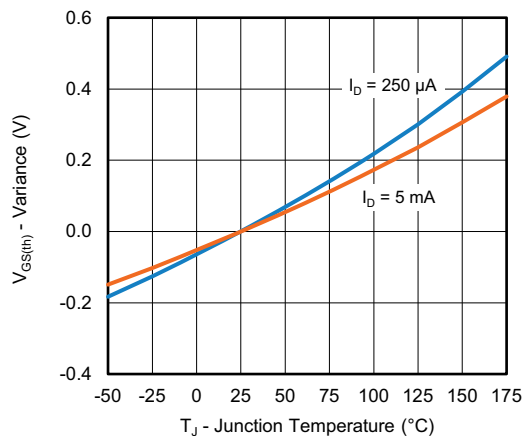
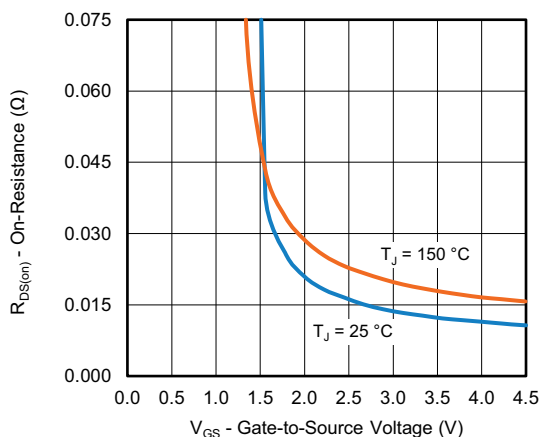
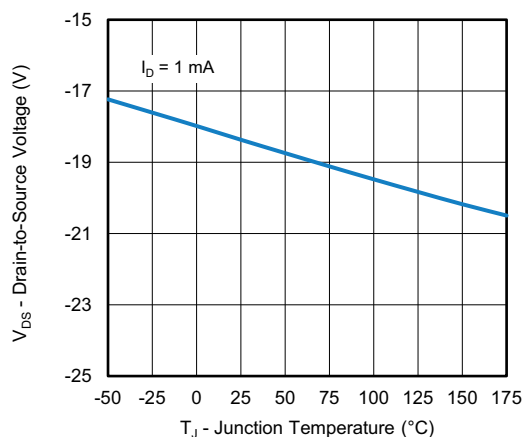
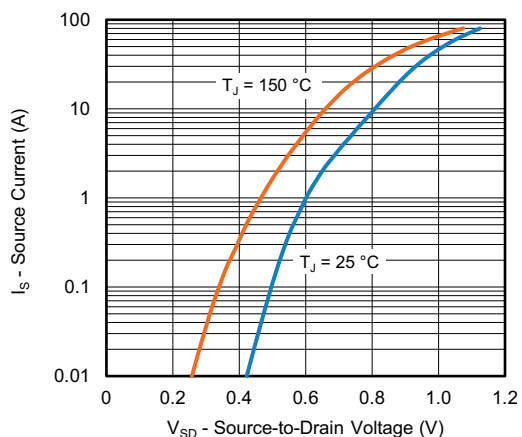
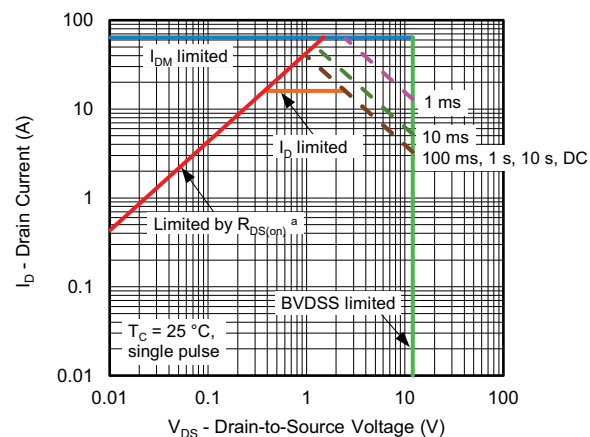
On-Resistance vs. Drain Current



Capacitance



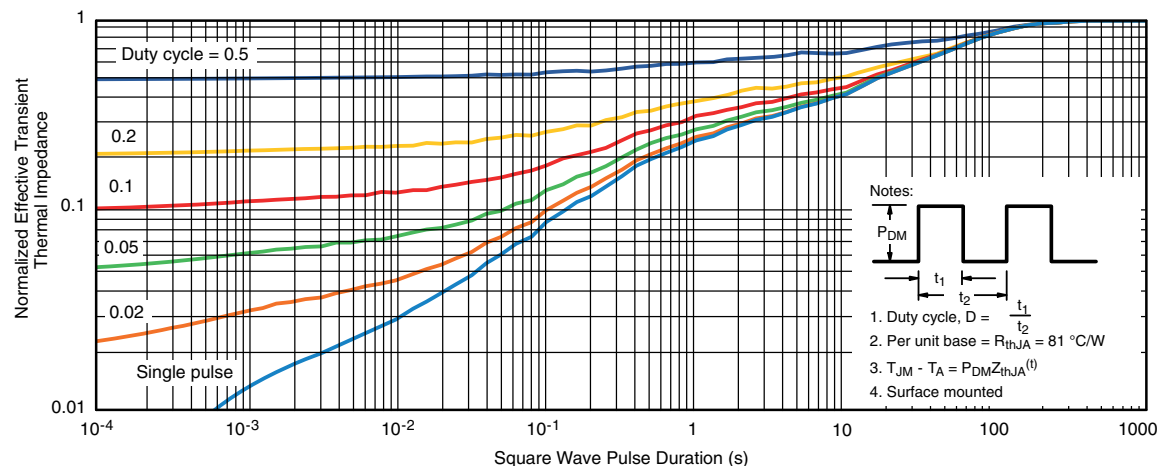
Gate Charge

TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)

On-Resistance vs. Junction Temperature

Threshold Voltage

On-Resistance vs. Gate-to-Source Voltage

Drain Source Breakdown vs. Junction Temperature

Source Drain Diode Forward Voltage

Safe Operating Area
Note

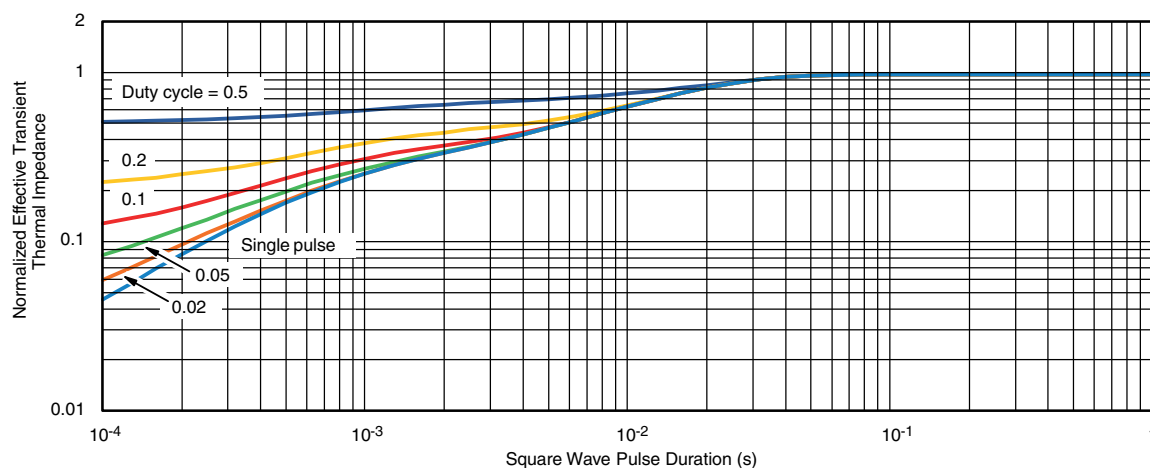
a. $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified



THERMAL RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



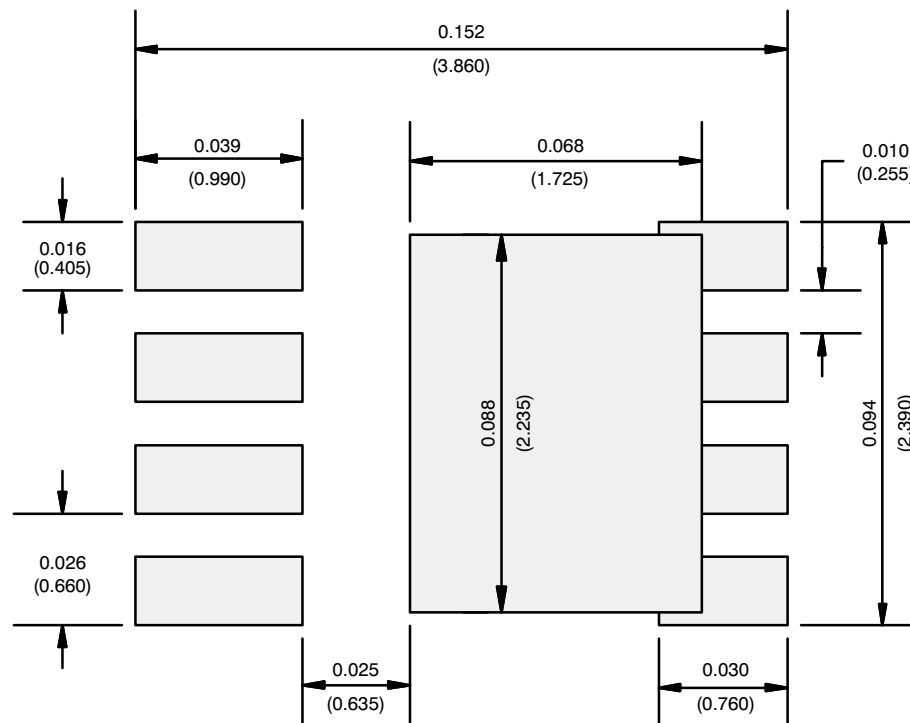
Normalized Thermal Transient Impedance, Junction-to-Case

Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient ($25\text{ }^{\circ}\text{C}$)
 - Normalized Transient Thermal Impedance Junction-to-Case ($25\text{ }^{\circ}\text{C}$)
 are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

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RECOMMENDED MINIMUM PADS FOR PowerPAK® 1212-8 Single



Recommended Minimum Pads
Dimensions in Inches/(mm)

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